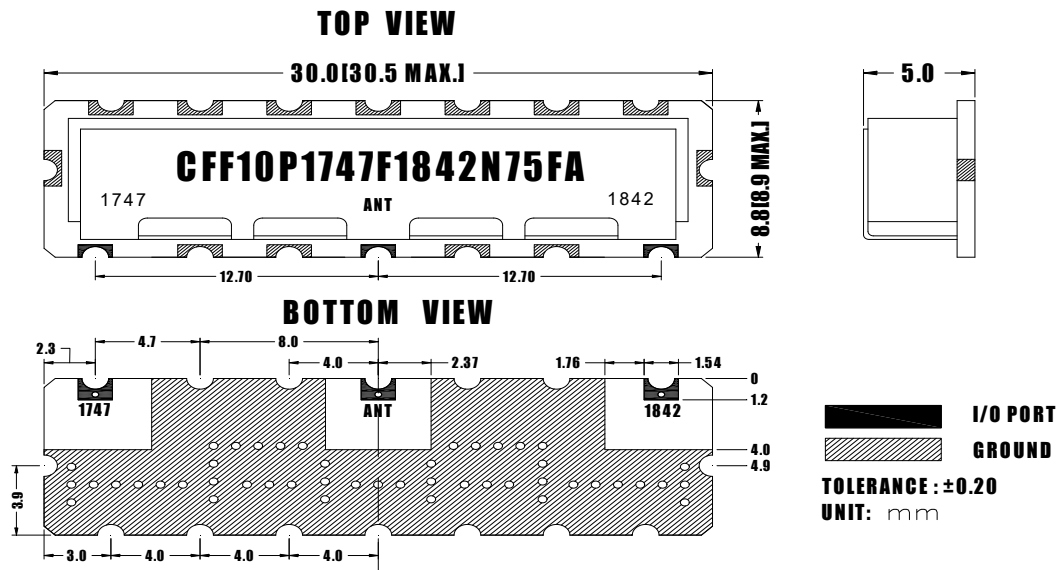


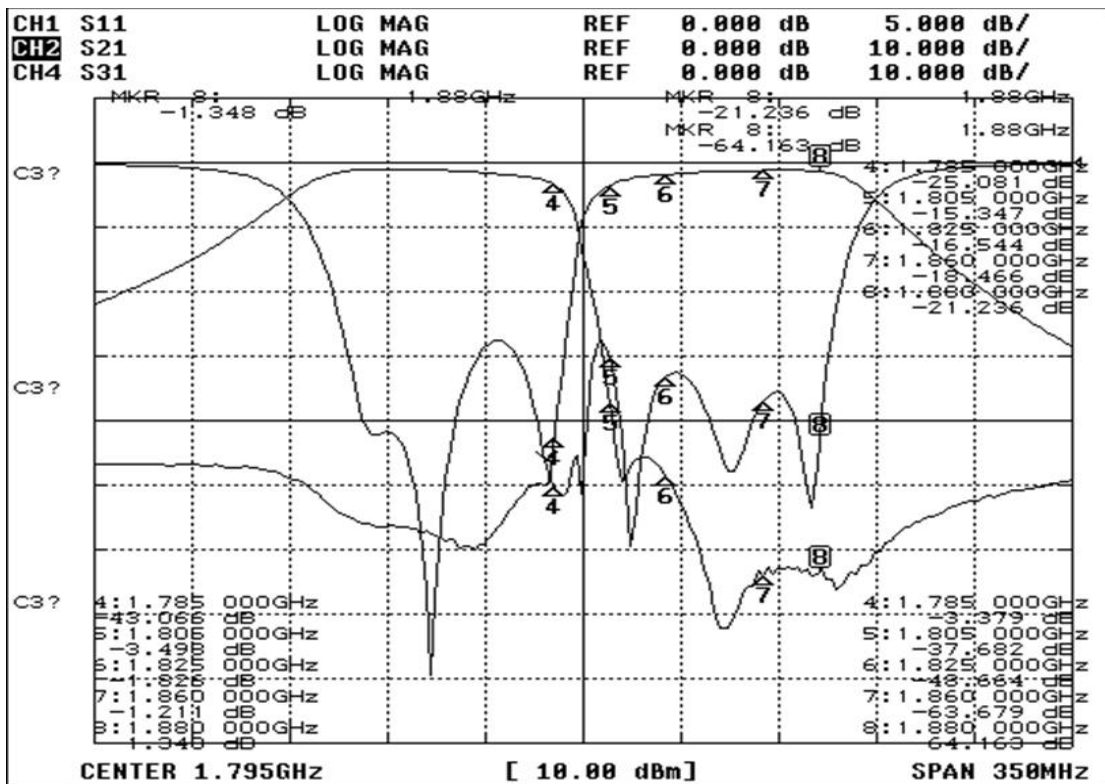
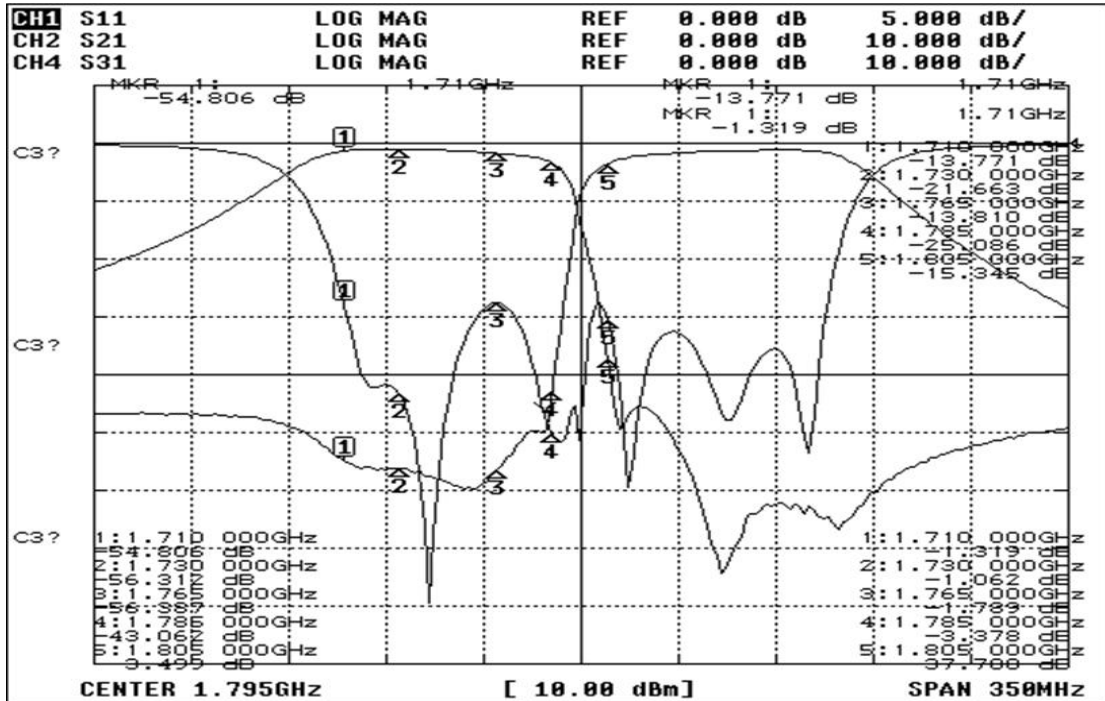
Electrical Specification

ITEMS	ANT>>LOW	ANT>>High	UNIT
Center Frequency [fo]	1842.5	1747.5	MHz
Bandwidth [BW]	fo ±37.5 [1805~1880]	fo ±37.5 [1710~1785]	MHz
Insertion Loss in BW	2.0dB max @ [TX:1860~1880]	2.0dB max@ [RX:1710~1730]	dB max
	2.0dB max @ [TX:1860~1880]	2.0dB max@ [RX:1710~1730]	dB max
Ripple in BW	2.0dB max @ [TX:1860~1880]	2.0dB max@ [RX:1710~1730]	dB max
	2.0dB max @ [TX:1860~1880]	2.0dB max@ [RX:1710~1730]	dB max
Return Loss in BW <input checked="" type="checkbox"/> ANT Port	14.0	14.0	dB min
VSW Rin BW <input checked="" type="checkbox"/> ALL Port			max
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	43.0dB typ. 40dB min@[1710~ 1785]		MHz
	43.0dB typ. 40dB min@[1710~ 1785]		MHz
	dB min @ fo ± [~]		MHz
	dB min @ fo ± [~]		MHz
Isolations	43.0dB typ. 40dB min@[1710~ 1785]		MHz
	43.0dB typ. 37dB min@[1805~ 1880]		MHz
Input Power	3		W max.
In/Out Impedance	50 Ω		
Operation Temperature Range	-40°C to +85°C		

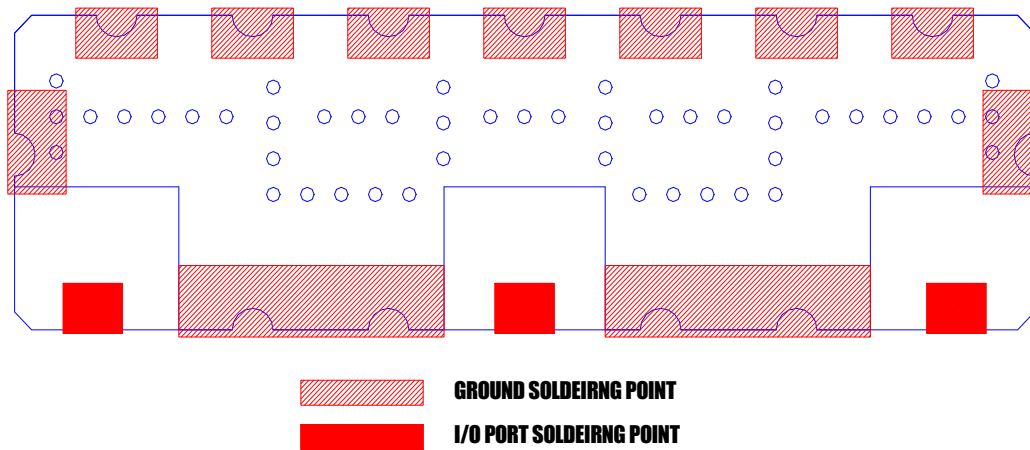
Mechanical Specification



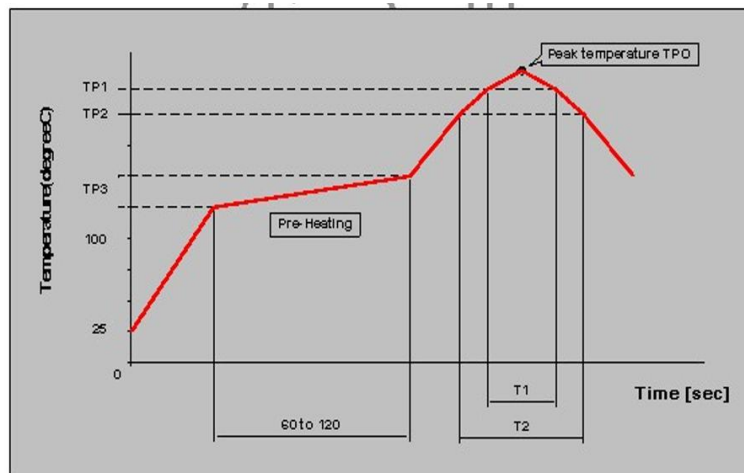
Plot Data



Recommneded PC Board Pattern



Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245±5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260±5/0	240	20	220	70	150 to 180